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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I ² C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	63
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 12bit SAR; D/A 12bit
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32tg11b540f64gq80-ar

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3.3 General Purpose Input/Output (GPIO)

EFM32TG11 has up to 67 General Purpose Input/Output pins. Each GPIO pin can be individually configured as either an output or input. More advanced configurations including open-drain, open-source, and glitch-filtering can be configured for each individual GPIO pin. The GPIO pins can be overridden by peripheral connections, like SPI communication. Each peripheral connection can be routed to several GPIO pins on the device. The input value of a GPIO pin can be routed through the Peripheral Reflex System to other peripherals. The GPIO subsystem supports asynchronous external pin interrupts.

3.4 Clocking

3.4.1 Clock Management Unit (CMU)

The Clock Management Unit controls oscillators and clocks in the EFM32TG11. Individual enabling and disabling of clocks to all peripheral modules is performed by the CMU. The CMU also controls enabling and configuration of the oscillators. A high degree of flexibility allows software to optimize energy consumption in any specific application by minimizing power dissipation in unused peripherals and oscillators.

3.4.2 Internal and External Oscillators

The EFM32TG11 supports two crystal oscillators and fully integrates four RC oscillators, listed below.

- A high frequency crystal oscillator (HFXO) with integrated load capacitors, tunable in small steps, provides a precise timing reference for the MCU. Crystal frequencies in the range from 4 to 48 MHz are supported. An external clock source such as a TCXO can also be applied to the HFXO input for improved accuracy over temperature.
- A 32.768 kHz crystal oscillator (LFXO) provides an accurate timing reference for low energy modes.
- An integrated high frequency RC oscillator (HFRCO) is available for the MCU system. The HFRCO employs fast startup at minimal energy consumption combined with a wide frequency range. When crystal accuracy is not required, it can be operated in free-running mode at a number of factory-calibrated frequencies. A digital phase-locked loop (DPLL) feature allows the HFRCO to achieve higher accuracy and stability by referencing other available clock sources such as LFXO and HFXO.
- An integrated auxiliary high frequency RC oscillator (AUXHFRCO) is available for timing the general-purpose ADC with a wide frequency range.
- An integrated low frequency 32.768 kHz RC oscillator (LFRCO) can be used as a timing reference in low energy modes, when crystal accuracy is not required.
- An integrated ultra-low frequency 1 kHz RC oscillator (ULFRCO) is available to provide a timing reference at the lowest energy consumption in low energy modes.

3.5 Counters/Timers and PWM

3.5.1 Timer/Counter (TIMER)

TIMER peripherals keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each TIMER is a 16-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the TIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit TIMER_0 only.

3.5.2 Wide Timer/Counter (WTIMER)

WTIMER peripherals function just as TIMER peripherals, but are 32 bits wide. They keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each WTIMER is a 32-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the WTIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit WTIMER_0 only.

3.5.3 Real Time Counter and Calendar (RTCC)

The Real Time Counter and Calendar (RTCC) is a 32-bit counter providing timekeeping in all energy modes. The RTCC includes a Binary Coded Decimal (BCD) calendar mode for easy time and date keeping. The RTCC can be clocked by any of the on-board oscillators with the exception of the AUXHFRCO, and it is capable of providing system wake-up at user defined instances. The RTCC includes 128 bytes of general purpose data retention, allowing easy and convenient data storage in all energy modes down to EM4H.

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on $T_{AMB}=25^{\circ}\text{C}$ and $V_{DD}=3.3\text{ V}$, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to [4.1.2.1 General Operating Conditions](#) for more details about operational supply and temperature limits.

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at <http://www.silabs.com/support/quality/pages/default.aspx>.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-50	—	150	$^{\circ}\text{C}$
Voltage on any supply pin	V_{DDMAX}		-0.3	—	3.8	V
Voltage ramp rate on any supply pin	$V_{DDRAMPMAX}$		—	—	1	V / μs
DC voltage on any GPIO pin	V_{DIGPIN}	5V tolerant GPIO pins ^{1 2 3}	-0.3	—	Min of 5.25 and IOVDD +2	V
		LCD pins ³	-0.3	—	Min of 3.8 and IOVDD +2	V
		Standard GPIO pins	-0.3	—	IOVDD+0.3	V
Total current into VDD power lines	I_{VDDMAX}	Source	—	—	200	mA
Total current into VSS ground lines	I_{VSSMAX}	Sink	—	—	200	mA
Current per I/O pin	I_{IOMAX}	Sink	—	—	50	mA
		Source	—	—	50	mA
Current for all I/O pins	$I_{IOALLMAX}$	Sink	—	—	200	mA
		Source	—	—	200	mA
Junction temperature	T_J	-G grade devices	-40	—	105	$^{\circ}\text{C}$
		-I grade devices	-40	—	125	$^{\circ}\text{C}$

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.
2. Valid for IOVDD in valid operating range or when IOVDD is undriven (high-Z). If IOVDD is connected to a low-impedance source below the valid operating range (e.g. IOVDD shorted to VSS), the pin voltage maximum is IOVDD + 0.3 V, to avoid exceeding the maximum IO current specifications.
3. To operate above the IOVDD supply rail, over-voltage tolerance must be enabled according to the GPIO_Px_OVTDIS register. Pins with over-voltage tolerance disabled have the same limits as Standard GPIO.

4.1.12 Voltage Monitor (VMON)

Table 4.19. Voltage Monitor (VMON)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current (including I _{SENSE})	I _{VMON}	In EM0 or EM1, 1 supply monitored, T ≤ 85 °C	—	6.3	TBD	μA
		In EM0 or EM1, 4 supplies monitored, T ≤ 85 °C	—	12.5	TBD	μA
		In EM2, EM3 or EM4, 1 supply monitored and above threshold	—	62	—	nA
		In EM2, EM3 or EM4, 1 supply monitored and below threshold	—	62	—	nA
		In EM2, EM3 or EM4, 4 supplies monitored and all above threshold	—	99	—	nA
		In EM2, EM3 or EM4, 4 supplies monitored and all below threshold	—	99	—	nA
Loading of monitored supply	I _{SENSE}	In EM0 or EM1	—	2	—	μA
		In EM2, EM3 or EM4	—	2	—	nA
Threshold range	V _{VMON_RANGE}		1.62	—	3.4	V
Threshold step size	N _{VMON_STESP}	Coarse	—	200	—	mV
		Fine	—	20	—	mV
Response time	t _{VMON_RES}	Supply drops at 1V/μs rate	—	460	—	ns
Hysteresis	V _{VMON_HYST}		—	26	—	mV

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal to noise and distortion ratio (1 kHz sine wave), Noise band limited to 250 kHz	SNDR _{DAC}	500 ksps, single-ended, internal 1.25V reference	—	60.4	—	dB
		500 ksps, single-ended, internal 2.5V reference	—	61.6	—	dB
		500 ksps, single-ended, 3.3V VDD reference	—	64.0	—	dB
		500 ksps, differential, internal 1.25V reference	—	63.3	—	dB
		500 ksps, differential, internal 2.5V reference	—	64.4	—	dB
		500 ksps, differential, 3.3V VDD reference	—	65.8	—	dB
Signal to noise and distortion ratio (1 kHz sine wave), Noise band limited to 22 kHz	SNDR _{DAC_BAND}	500 ksps, single-ended, internal 1.25V reference	—	65.3	—	dB
		500 ksps, single-ended, internal 2.5V reference	—	66.7	—	dB
		500 ksps, differential, 3.3V VDD reference	—	68.5	—	dB
		500 ksps, differential, internal 1.25V reference	—	67.8	—	dB
		500 ksps, differential, internal 2.5V reference	—	69.0	—	dB
		500 ksps, single-ended, 3.3V VDD reference	—	70.0	—	dB
Total harmonic distortion	THD		—	70.2	—	dB
Differential non-linearity ³	DNL _{DAC}		TBD	—	TBD	LSB
Integral non-linearity	INL _{DAC}		TBD	—	TBD	LSB
Offset error ⁵	V _{OFFSET}	T = 25 °C	TBD	—	TBD	mV
		Across operating temperature range	TBD	—	TBD	mV
Gain error ⁵	V _{GAIN}	T = 25 °C, Low-noise internal reference (REFSEL = 1V25LN or 2V5LN)	TBD	—	TBD	%
		Across operating temperature range, Low-noise internal reference (REFSEL = 1V25LN or 2V5LN)	TBD	—	TBD	%
External load capacitance, OUTSCALE=0	C _{LOAD}		—	—	75	pF

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Open-loop gain	G _{OL}	DRIVESTRENGTH = 3	—	135	—	dB
		DRIVESTRENGTH = 2	—	137	—	dB
		DRIVESTRENGTH = 1	—	121	—	dB
		DRIVESTRENGTH = 0	—	109	—	dB
Loop unit-gain frequency ⁷	UGF	DRIVESTRENGTH = 3, Buffer connection	—	3.38	—	MHz
		DRIVESTRENGTH = 2, Buffer connection	—	0.9	—	MHz
		DRIVESTRENGTH = 1, Buffer connection	—	132	—	kHz
		DRIVESTRENGTH = 0, Buffer connection	—	34	—	kHz
		DRIVESTRENGTH = 3, 3x Gain connection	—	2.57	—	MHz
		DRIVESTRENGTH = 2, 3x Gain connection	—	0.71	—	MHz
		DRIVESTRENGTH = 1, 3x Gain connection	—	113	—	kHz
		DRIVESTRENGTH = 0, 3x Gain connection	—	28	—	kHz
Phase margin	PM	DRIVESTRENGTH = 3, Buffer connection	—	67	—	°
		DRIVESTRENGTH = 2, Buffer connection	—	69	—	°
		DRIVESTRENGTH = 1, Buffer connection	—	63	—	°
		DRIVESTRENGTH = 0, Buffer connection	—	68	—	°
Output voltage noise	N _{OUT}	DRIVESTRENGTH = 3, Buffer connection, 10 Hz - 10 MHz	—	146	—	μVrms
		DRIVESTRENGTH = 2, Buffer connection, 10 Hz - 10 MHz	—	163	—	μVrms
		DRIVESTRENGTH = 1, Buffer connection, 10 Hz - 1 MHz	—	170	—	μVrms
		DRIVESTRENGTH = 0, Buffer connection, 10 Hz - 1 MHz	—	176	—	μVrms
		DRIVESTRENGTH = 3, 3x Gain connection, 10 Hz - 10 MHz	—	313	—	μVrms
		DRIVESTRENGTH = 2, 3x Gain connection, 10 Hz - 10 MHz	—	271	—	μVrms
		DRIVESTRENGTH = 1, 3x Gain connection, 10 Hz - 1 MHz	—	247	—	μVrms
		DRIVESTRENGTH = 0, 3x Gain connection, 10 Hz - 1 MHz	—	245	—	μVrms

4.1.21.3 I2C Fast-mode Plus (Fm+)¹

Table 4.30. I2C Fast-mode Plus (Fm+)¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency ²	f _{SCL}		0	—	1000	kHz
SCL clock low time	t _{LOW}		0.5	—	—	μs
SCL clock high time	t _{HIGH}		0.26	—	—	μs
SDA set-up time	t _{SU_DAT}		50	—	—	ns
SDA hold time	t _{HD_DAT}		100	—	—	ns
Repeated START condition set-up time	t _{SU_STA}		0.26	—	—	μs
(Repeated) START condition hold time	t _{HD_STA}		0.26	—	—	μs
STOP condition set-up time	t _{SU_STO}		0.26	—	—	μs
Bus free time between a STOP and START condition	t _{BUF}		0.5	—	—	μs

Note:

1. For CLHR set to 0 or 1 in the I2Cn_CTRL register.
2. For the minimum HPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual.

SPI Slave Timing

Table 4.32. SPI Slave Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCLK period ^{1 3 2}	t_{SCLK}		6 * $t_{HFERCLK}$	—	—	ns
SCLK high time ^{1 3 2}	t_{SCLK_HI}		2.5 * $t_{HFERCLK}$	—	—	ns
SCLK low time ^{1 3 2}	t_{SCLK_LO}		2.5 * $t_{HFERCLK}$	—	—	ns
CS active to MISO ^{1 3}	$t_{CS_ACT_MI}$		20	—	70	ns
CS disable to MISO ^{1 3}	$t_{CS_DIS_MI}$		15	—	150	ns
MOSI setup time ^{1 3}	t_{SU_MO}		4	—	—	ns
MOSI hold time ^{1 3 2}	t_{H_MO}		7	—	—	ns
SCLK to MISO ^{1 3 2}	t_{SCLK_MI}		14 + 1.5 * $t_{HFERCLK}$	—	40 + 2.5 * $t_{HFERCLK}$	ns

Note:

1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0).
2. $t_{HFERCLK}$ is one period of the selected HFERCLK.
3. Measurement done with 8 pF output loading at 10% and 90% of V_{DD} (figure shows 50% of V_{DD}).

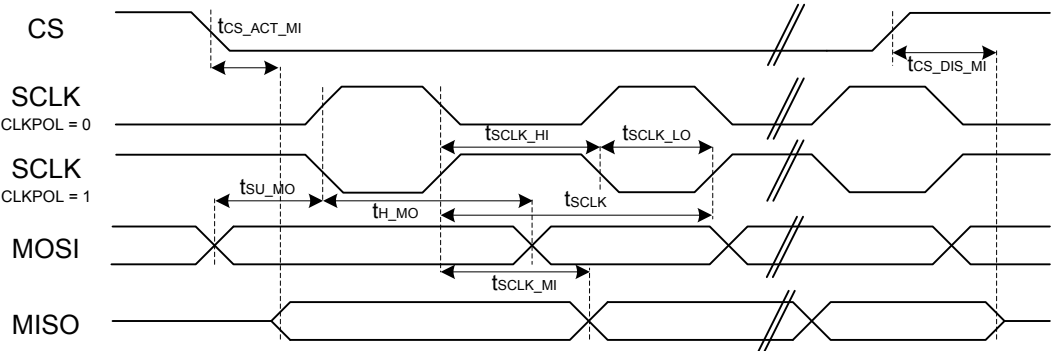


Figure 4.2. SPI Slave Timing Diagram

4.2 Typical Performance Curves

Typical performance curves indicate typical characterized performance under the stated conditions.

4.2.1 Supply Current

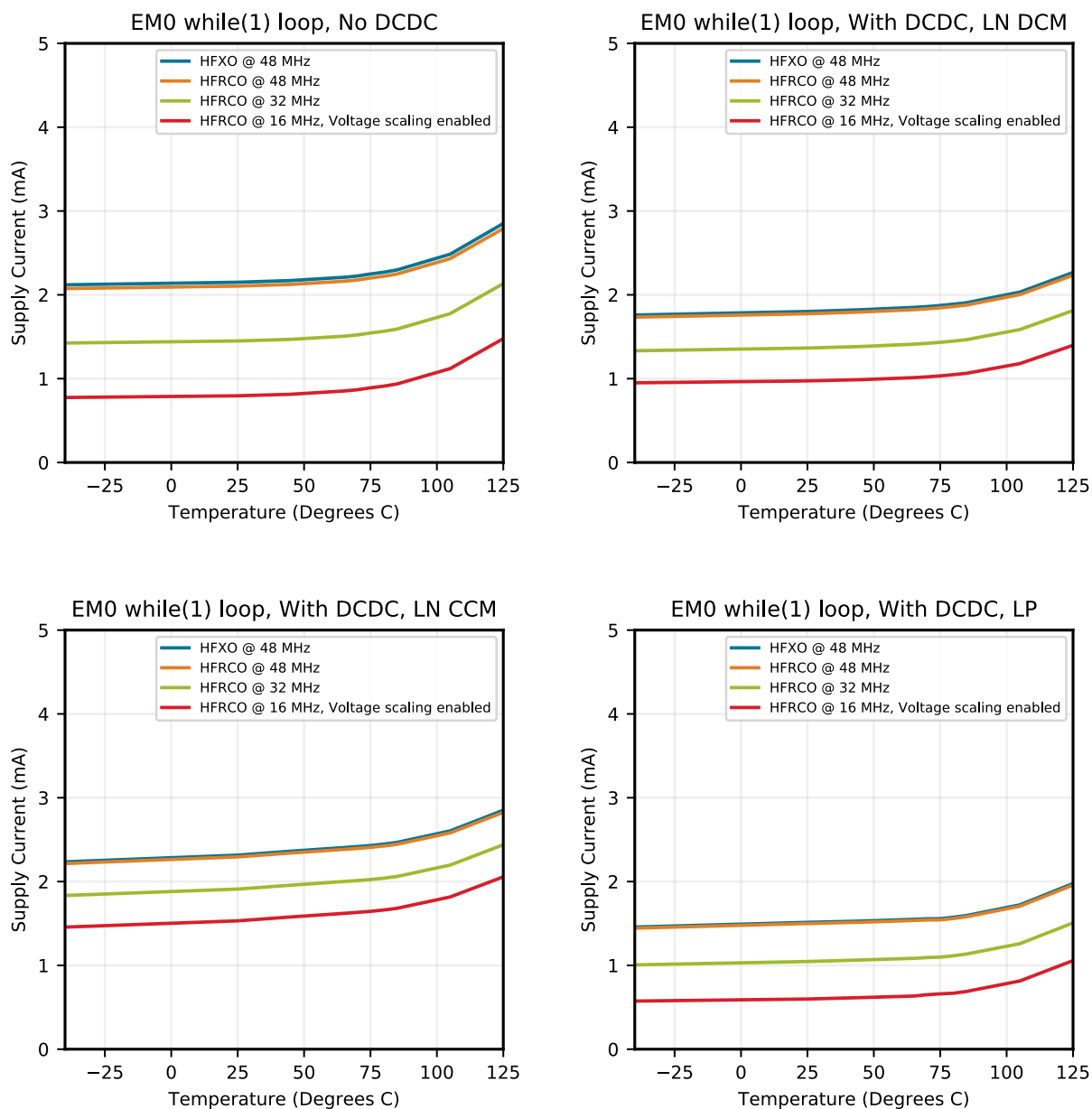


Figure 4.3. EM0 Active Mode Typical Supply Current vs. Temperature

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB4	10	GPIO	PB5	11	GPIO
PB6	12	GPIO	PC0	13	GPIO (5V)
PC1	14	GPIO (5V)	PC2	15	GPIO (5V)
PC3	16	GPIO (5V)	PC4	17	GPIO
PC5	18	GPIO	PB7	19	GPIO
PB8	20	GPIO	PA8	21	GPIO
PA9	22	GPIO	PA10	23	GPIO
PA12	24	GPIO	PA13	25	GPIO (5V)
PA14	26	GPIO	RESETn	27	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	28	GPIO	PB12	29	GPIO
AVDD	30 34	Analog power supply.	PB13	31	GPIO
PB14	32	GPIO	PD0	35	GPIO (5V)
PD1	36	GPIO	PD2	37	GPIO (5V)
PD3	38	GPIO	PD4	39	GPIO
PD5	40	GPIO	PD6	41	GPIO
PD7	42	GPIO	PD8	43	GPIO
PC6	44	GPIO	PC7	45	GPIO
VREGSW	47	DCDC regulator switching node	VREGVDD	48	Voltage regulator VDD input
DVDD	49	Digital power supply.	DECOUPLE	50	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	52	GPIO	PE5	53	GPIO
PE6	54	GPIO	PE7	55	GPIO
PC8	56	GPIO	PC9	57	GPIO
PC10	58	GPIO (5V)	PC11	59	GPIO (5V)
PC12	60	GPIO (5V)	PC13	61	GPIO (5V)
PC14	62	GPIO (5V)	PC15	63	GPIO (5V)
PF0	64	GPIO (5V)	PF1	65	GPIO (5V)
PF2	66	GPIO	PF3	67	GPIO
PF4	68	GPIO	PF5	69	GPIO
PE8	71	GPIO	PE9	72	GPIO
PE10	73	GPIO	PE11	74	GPIO
BODEN	75	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.	PE12	76	GPIO
PE13	77	GPIO	PE14	78	GPIO

5.4 EFM32TG11B3xx in QFP64 Device Pinout

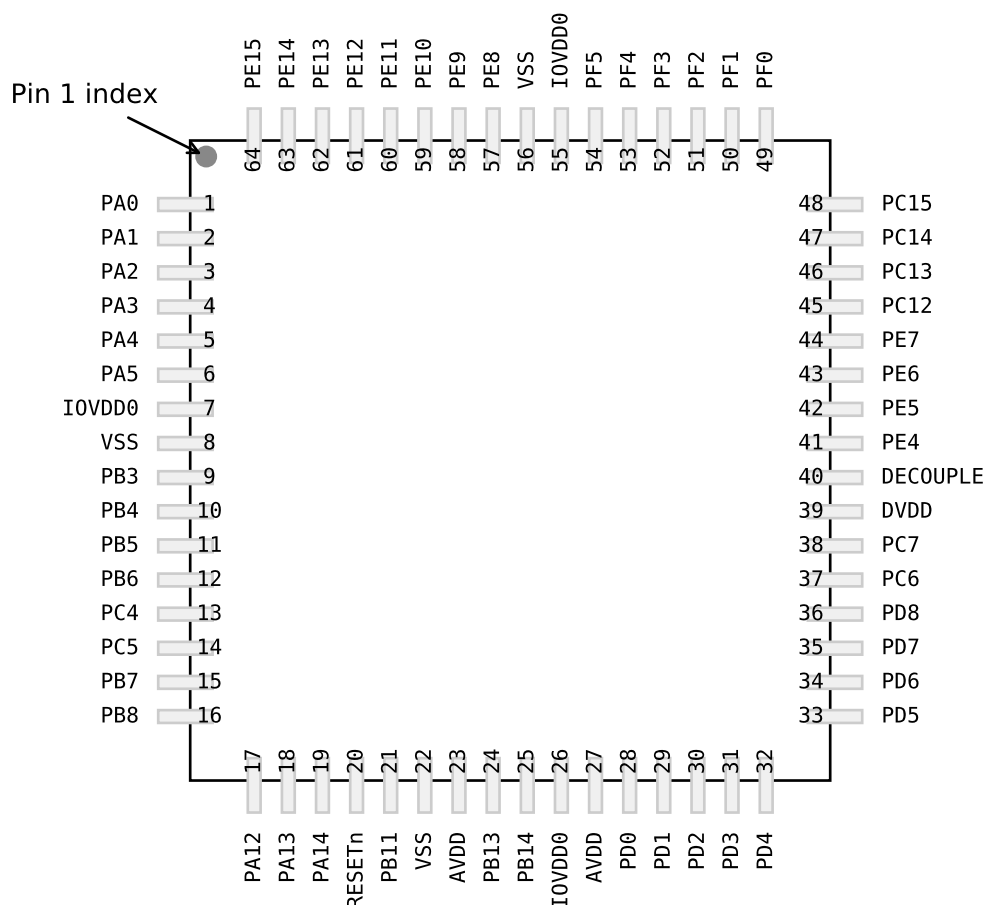


Figure 5.4. EFM32TG11B3xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.4. EFM32TG11B3xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB4	10	GPIO	PB5	11	GPIO
PB6	12	GPIO	PC4	13	GPIO
PC5	14	GPIO	PB7	15	GPIO
PB8	16	GPIO	PA8	17	GPIO
PA12	18	GPIO	PA13	19	GPIO (5V)
PA14	20	GPIO	RESETn	21	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	22	GPIO	PB12	23	GPIO
AVDD	24 28	Analog power supply.	PB13	25	GPIO
PB14	26	GPIO	PD0	29	GPIO (5V)
PD1	30	GPIO	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC7	37	GPIO
VREGSW	39	DCDC regulator switching node	VREGVDD	40	Voltage regulator VDD input
DVDD	41	Digital power supply.	DECOUPLE	42	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	43	GPIO	PE5	44	GPIO
PE6	45	GPIO	PE7	46	GPIO
PC12	47	GPIO (5V)	PC13	48	GPIO (5V)
PF0	49	GPIO (5V)	PF1	50	GPIO (5V)
PF2	51	GPIO	PF3	52	GPIO
PF4	53	GPIO	PF5	54	GPIO
PE8	56	GPIO	PE9	57	GPIO
PE10	58	GPIO	PE11	59	GPIO
PE12	60	GPIO	PE13	61	GPIO
PE14	62	GPIO	PE15	63	GPIO
PA15	64	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

5.8 EFM32TG11B1xx in QFN64 Device Pinout

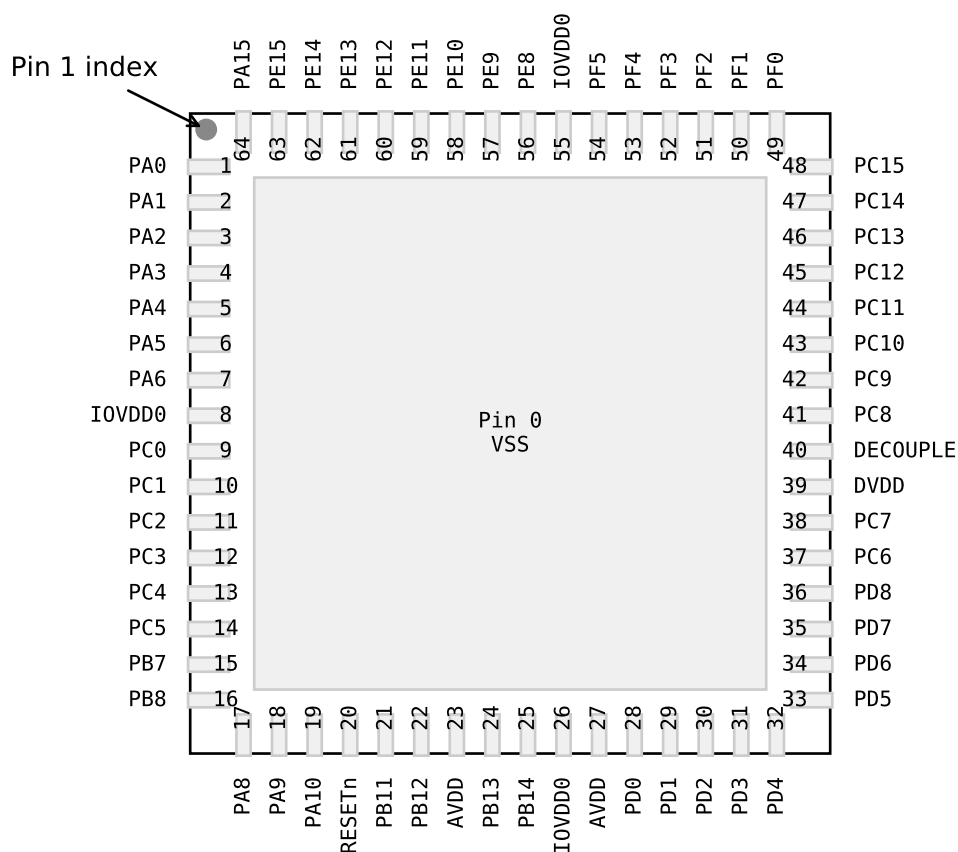


Figure 5.8. EFM32TG11B1xx in QFN64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.8. EFM32TG11B1xx in QFN64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
VREGVSS	0	Voltage regulator VSS	PA0	1	GPIO
PA1	2	GPIO	PA2	3	GPIO
PA3	4	GPIO	PA4	5	GPIO
PA5	6	GPIO	PA6	7	GPIO
IOVDD0	8 26 55	Digital IO power supply 0.	PC0	9	GPIO (5V)
PC1	10	GPIO (5V)	PC2	11	GPIO (5V)

5.10 EFM32TG11B3xx in QFP48 Device Pinout

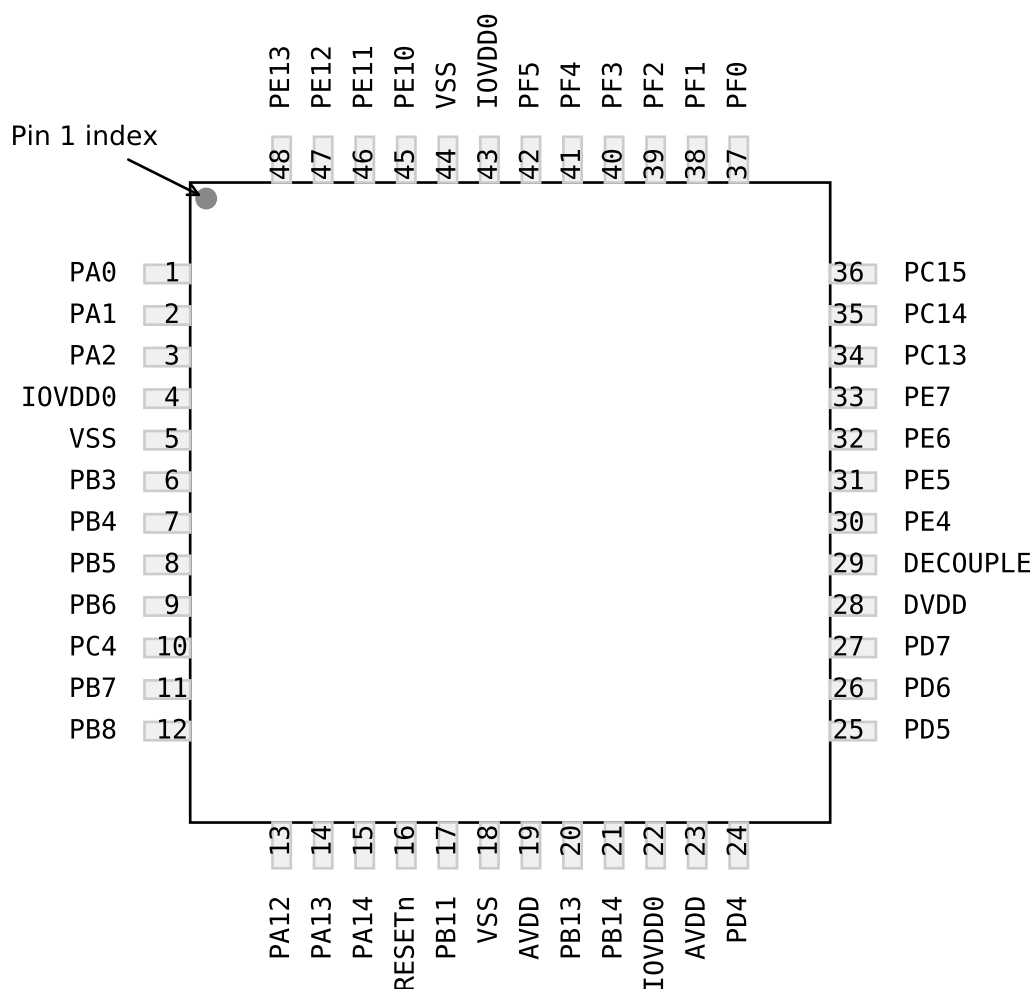


Figure 5.10. EFM32TG11B3xx in QFP48 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.10. EFM32TG11B3xx in QFP48 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	IOVDD0	4 22 43	Digital IO power supply 0.
VSS	5 18 44	Ground	PB3	6	GPIO
PB4	7	GPIO	PB5	8	GPIO
PB6	9	GPIO	PC4	10	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA14	8	GPIO	RESETn	9	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	10	GPIO	AVDD	11	Analog power supply.
PB13	12	GPIO	PB14	13	GPIO
PD4	15	GPIO	PD5	16	GPIO
PD6	17	GPIO	PD7	18	GPIO
VREGSW	20	DCDC regulator switching node	VREGVDD	21	Voltage regulator VDD input
DVDD	22	Digital power supply.	DECOUPLE	23	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	24	GPIO	PE5	25	GPIO
PC15	26	GPIO (5V)	PF0	27	GPIO (5V)
PF1	28	GPIO (5V)	PF2	29	GPIO
PE11	31	GPIO	PE12	32	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).

GPIO Name	Pin Alternate Functionality / Description			
	Analog	Timers	Communication	Other
PD5	BUSADC0Y BUSADC0X OPA2_OUT	WTIM0_CDTI1 #4 WTIM1_CC3 #1	US1_RTS #1 U0_CTS #5 LEU0_RX #0 I2C1_SCL #3	
PD6	BUSADC0Y BUSADC0X ADC0_EXTP VDAC0_EXT OPA1_P	TIM1_CC0 #4 WTIM0_CDTI2 #4 WTIM1_CC0 #2 LE- TIM0_OUT0 #0 PCNT0_S0IN #3	US0_RTS #5 US1_RX #2 US2_CTS #5 US3_CTS #2 U0_RTS #5 I2C0_SDA #1	CMU_CLK2 #2 LES_AL- TEX0 PRS_CH5 #2 ACMP0_O #2
PD7	BUSADC0Y BUSADC0X ADC0_EXTN OPA1_N	TIM1_CC1 #4 WTIM1_CC1 #2 LE- TIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 US3_CLK #1 U0_TX #6 I2C0_SCL #1	CMU_CLK0 #2 LES_AL- TEX1 ACMP1_O #2
PD8	BU_VIN	WTIM1_CC2 #2	US2_RTS #5	CMU_CLK1 #1
PC6	BUSACMP0Y BU- SACMP0X OPA3_P LCD_SEG32	WTIM1_CC3 #2	US0_RTS #2 US1_CTS #3 I2C0_SDA #2	LES_CH6
PC7	BUSACMP0Y BU- SACMP0X OPA3_N LCD_SEG33	WTIM1_CC0 #3	US0_CTS #2 US1_RTS #3 I2C0_SCL #2	LES_CH7
PE4	BUSDY BUSCX LCD_COM0	WTIM0_CC0 #0 WTIM1_CC1 #4	US0_CS #1 US1_CS #5 US3_CS #1 U0_RX #6 I2C0_SDA #7	
PE5	BUSCY BUSDX LCD_COM1	WTIM0_CC1 #0 WTIM1_CC2 #4	US0_CLK #1 US1_CLK #6 US3_CTS #1 I2C0_SCL #7	
PE6	BUSDY BUSCX LCD_COM2	WTIM0_CC2 #0 WTIM1_CC3 #4	US0_RX #1 US3_TX #1	PRS_CH6 #2
PE7	BUSCY BUSDX LCD_COM3	WTIM1_CC0 #5	US0_TX #1 US3_RX #1	PRS_CH7 #2
PC8	BUSACMP1Y BU- SACMP1X LCD_SEG34		US0_CS #2	LES_CH8 PRS_CH4 #0
PC9	BUSACMP1Y BU- SACMP1X LCD_SEG35		US0_CLK #2	LES_CH9 PRS_CH5 #0 GPIO_EM4WU2
PC10	BUSACMP1Y BU- SACMP1X		US0_RX #2	LES_CH10
PC11	BUSACMP1Y BU- SACMP1X		US0_TX #2 I2C1_SDA #4	LES_CH11
PC12	VDAC0_OUT1ALT / OPA1_OUTALT #0 BU- SACMP1Y BUSACMP1X	TIM1_CC3 #0	US0_RTS #3 US1_CTS #4 US2_CTS #4 U0_RTS #3	CMU_CLK0 #1 LES_CH12
PC13	VDAC0_OUT1ALT / OPA1_OUTALT #1 BU- SACMP1Y BUSACMP1X	TIM0_CDTI0 #1 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0	US0_CTS #3 US1_RTS #4 US2_RTS #4 U0_CTS #3	LES_CH13
PC14	VDAC0_OUT1ALT / OPA1_OUTALT #2 BU- SACMP1Y BUSACMP1X	TIM0_CDTI1 #1 TIM1_CC1 #0 TIM1_CC3 #4 LETIM0_OUT0 #5 PCNT0_S1IN #0	US0_CS #3 US1_CS #3 US2_RTS #3 US3_CS #2 U0_TX #3 LEU0_TX #5	LES_CH14 PRS_CH0 #2

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LCD_SEG9	0: PE13		LCD segment line 9.
LCD_SEG10	0: PE14		LCD segment line 10.
LCD_SEG11	0: PE15		LCD segment line 11.
LCD_SEG12	0: PA15		LCD segment line 12.
LCD_SEG13	0: PA0		LCD segment line 13.
LCD_SEG14	0: PA1		LCD segment line 14.
LCD_SEG15	0: PA2		LCD segment line 15.
LCD_SEG16	0: PA3		LCD segment line 16.
LCD_SEG17	0: PA4		LCD segment line 17.
LCD_SEG18	0: PA5		LCD segment line 18.
LCD_SEG19	0: PA6		LCD segment line 19.
LCD_SEG20 / LCD_COM4	0: PB3		LCD segment line 20. This pin may also be used as LCD COM line 4
LCD_SEG21 / LCD_COM5	0: PB4		LCD segment line 21. This pin may also be used as LCD COM line 5

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US2_CLK	0: PC4 1: PB5 2: PA9 3: PA15	5: PF2	USART2 clock input / output.
US2_CS	0: PC5 1: PB6 2: PA10 3: PB11	5: PF5	USART2 chip select input / output.
US2_CTS	0: PC1 1: PB12	4: PC12 5: PD6	USART2 Clear To Send hardware flow control input.
US2_RTS	0: PC0 2: PA12 3: PC14	4: PC13 5: PD8	USART2 Request To Send hardware flow control output.
US2_RX	0: PC3 1: PB4 2: PA8 3: PA14	5: PF1	USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	0: PC2 1: PB3 3: PA13	5: PF0	USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
US3_CLK	0: PA2 1: PD7 2: PD4		USART3 clock input / output.
US3_CS	0: PA3 1: PE4 2: PC14 3: PC0		USART3 chip select input / output.
US3_CTS	0: PA4 1: PE5 2: PD6		USART3 Clear To Send hardware flow control input.
US3_RTS	0: PA5 1: PC1 2: PA14 3: PC15		USART3 Request To Send hardware flow control output.
US3_RX	0: PA1 1: PE7 2: PB7		USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PA0 1: PE6 2: PB3		USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
VDAC0_EXT	0: PD6		Digital to analog converter VDAC0 external reference input pin.

5.16 Analog Port (APORT) Client Maps

The Analog Port (APORT) is an infrastructure used to connect chip pins with on-chip analog clients such as analog comparators, ADCs, DACs, etc. The APORT consists of a set of shared buses, switches, and control logic needed to configurably implement the signal routing. Figure 5.14 APORT Connection Diagram on page 119 shows the APORT routing for this device family (note that available features may vary by part number). A complete description of APORT functionality can be found in the Reference Manual.

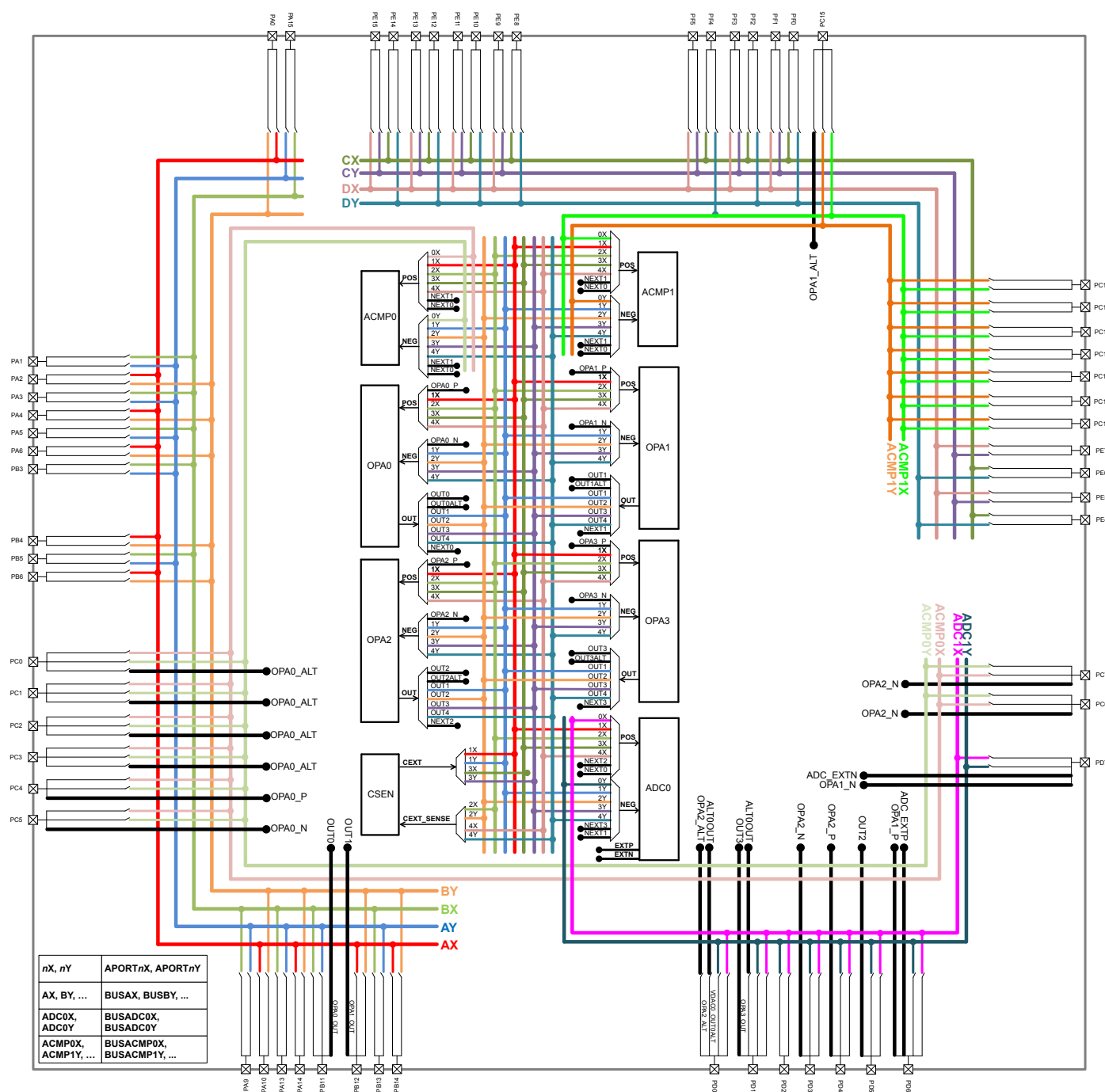


Figure 5.14. APORT Connection Diagram

Client maps for each analog circuit using the APORT are shown in the following tables. The maps are organized by bus, and show the peripheral's port connection, the shared bus, and the connection from specific bus channel numbers to GPIO pins.

In general, enumerations for the pin selection field in an analog peripheral's register can be determined by finding the desired pin connection in the table and then combining the value in the Port column (APORT__), and the channel identifier (CH__). For example, if pin

10. TQFP48 Package Specifications

10.1 TQFP48 Package Dimensions

